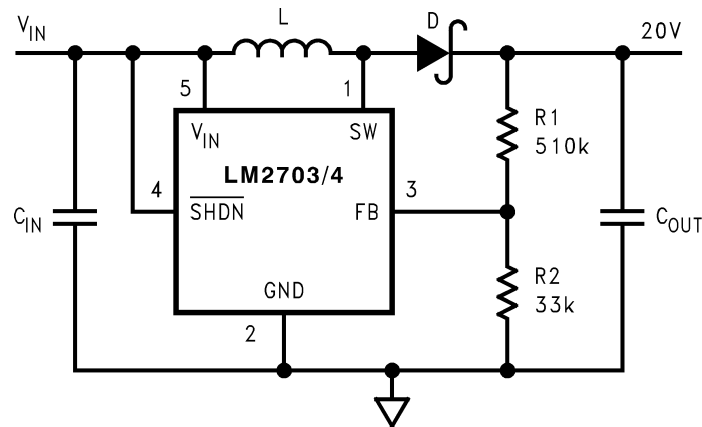


AN–1277 LM2703/LM2704 Evaluation Board

1 LM2703/LM2704 Evaluation Board



2 Bill of Materials

Components	LM2703	LM2704
L	10 μ H, DT1608C-103, Coilcraft	10 μ H, DO1608C-103, Coilcraft
C _{IN}	4.7 μ F, 10V Ceramic LMK316BJ475ML, Taiyo-Yuden	4.7 μ F, 10V Ceramic LMK316BJ475ML, Taiyo-Yuden
C _{OUT}	1 μ F, 25V Ceramic GMK316BJ105L, Taiyo-Yuden	4.7 μ F, 25V Ceramic MK325BJ475MN, Taiyo-Yuden
D	MBRM130LT3, ON Semi	MBRM130LT3, ON Semi

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